

**IN THE CLAIMS:**

1. (Original) An LED mounting module, comprising:

a substrate; and

a reflecting member made of a resin material and having a reflecting hole in a position corresponding to an LED device which is to be mounted on one of main surfaces of the substrate, wherein

the substrate and the reflecting member are directly adhered to each other in such a state that the main surface of the substrate is in contact with one of main surfaces of the reflecting member.

2. (Original) The LED mounting module of Claim 1, wherein

the substrate includes an insulation board made of a resin material, and a wiring pattern on one of main surfaces of the insulation board, and

the resin material forming the insulation board contains a same resin as the resin material forming the reflecting member.

3. (Original) The LED mounting module of Claim 1, wherein

the resin material is a thermosetting resin material principally containing an epoxy resin.

4. (Original) The LED mounting module of Claim 1, wherein

the resin material is a thermoplastic resin material principally containing a resin selected from a group consisting of a polyphthalamide resin, a liquid crystal polymer, a polyphenylene sulfide resin, and a polybutylene terephthalate resin.

5. (Original) The LED mounting module of Claim 1, wherein  
the resin material contains one or more fillers to improve reflection efficiency.
6. (Original) The LED mounting module of Claim 5, wherein  
the fillers include at least one of  $\text{TiO}_2$ ,  $\text{SiO}_2$ ,  $\text{Al}_2\text{O}_3$ , and  $\text{BaSO}_4$ .
7. (Original) The LED mounting module of Claim 2, wherein  
the resin material forming the insulation board contains at least one of  $\text{Al}_2\text{O}_3$ ,  $\text{AlN}$ ,  $\text{SiO}_2$ , and  $\text{SiC}$ .
8. (Original) The LED mounting module of Claim 2, wherein  
a metal board is provided on the other main surface of the substrate, and  
the resin material forming the insulation board is a composite material containing  
an inorganic filler and a thermosetting resin material.
9. (Original) The LED mounting module of Claim 2, wherein  
a metal board is provided on the other main surface of the substrate, and  
the resin material forming the insulation board is a thermosetting resin material  
containing a glass fiber.
10. (Original) The LED mounting module of Claim 1, wherein  
a depression is formed in a part of the substrate at which the reflecting member is  
adhered, and  
the depression is filled with the resin material forming the reflecting member.

11. (Original) The LED mounting module of Claim 1, wherein  
the LED device is one of a plurality of LED devices that are to be mounted on the  
main surface of the substrate, and  
the reflecting hole is one of a plurality of reflecting holes formed in the reflecting  
5 member in correspondence with the plurality of LED devices.
12. (Original) The LED mounting module of Claim 1, wherein  
the substrate includes an insulation board made of a ceramic material, and a  
wiring pattern on one of main surfaces of the insulation board.
13. (Original) The LED mounting module of Claim 12, wherein  
the ceramic material contains at least one of  $\text{Al}_2\text{O}_3$ ,  $\text{AlN}$ ,  $\text{SiO}_2$ , and  $\text{SiC}$ .
14. (Original) An LED module comprising:  
the LED mounting module defined in Claim 1; and  
an LED device mounted on the LED mounting module.
- 15.-27. (Cancelled)